



CURRENT LISTING OF CLAIMS

This listing of claims replaces all previous listing of claims. Kindly amend the claims as follows:

1. (Previously presented) An apparatus for attaching a leaded component to a substrate, comprising:

a mounting plate having a base portion, a first side wall extending from a first side of the base portion in a first direction, a second side wall extending in the first direction from a second side of the base portion that is axially aligned to the first side of the base portion, and at least one mounting flange extending from the first side wall and at least one mounting flange extending from the second side wall and at least one hole extending through the base portion of the mounting plate through which to pass a lead of a component; and

a heat sink, separate and distinct from the mounting plate, that is removably secured relative to the mounting plate by the mounting flanges.

2. (Canceled).

3. (Original) The apparatus according to claim 1, wherein the mounting flanges secures the component to the mounting plate.

4. (Original) The apparatus according to claim 1, wherein the heat sink includes a lower surface oriented toward the component and an upper surface and wherein the mounting flanges contact the upper surface of the heat sink to downwardly bias the heat sink.

5. (Previously presented) The apparatus according to claim 1, wherein the mounting flanges include holes for a fastener.
6. (Previously presented) The apparatus according to claim 5, wherein the heat sink includes holes for the fastener to fasten the heat sink to the mounting flanges.
7. (Original) The apparatus according to claim 6, wherein the fastener includes one of a screw, a rivet, and a bolt.
8. (Original) The apparatus according to claim 1, further comprising a thermal interface material adjoining a lower surface of the heat sink.
9. (Previously presented) The apparatus according to claim 8, wherein the lower surface of the base portion of the mounting plate is fastened to a substrate and the heat sink is mounted to the mounting flanges and the lower surface of the heat sink is in thermal communication with an upper surface of the component through the thermal interface material.
10. (Previously presented) The apparatus according to claim 9, wherein the side walls and flanges partially surround the component.
11. (Original) The apparatus according to claim 9, wherein the mounting plate is electrically insulated.

12. (Original) The apparatus according to claim 9, wherein the mounting plate is electrically conductive and is coupled to an electrical potential provided by the substrate.

13. (Canceled).

14. (Canceled).

15. (Canceled).

16. (Previously presented) The apparatus according to claim 1, wherein the base portion of the mounting plate includes fewer holes than the number of leads of the component.

17. (Original) The apparatus according to claim 1, wherein the component is a surface mounted component.

18. (Original) The apparatus according to claim 1, wherein the component is a through hole mounted component.

19. (Previously presented) A method of mounting a heat sink, comprising:
affixing a mounting plate having a base portion, a first side wall extending from a first side of the base portion in a first direction, a second side wall extending in the first direction from a second side of the base portion that is axially aligned to the first side of the base portion,

at least one mounting flange extending from the first side wall, at least one mounting flange extending from the second side wall and at least one hole extending through the base portion of the mounting plate through which to pass a lead of a component to a substrate;

mounting the leads of the component to the substrate through the at least one hole; and

fastening a removable heat sink that is separate and distinct from the mounting plate to the mounting flanges.

20. (Original) The method according to claim 19, wherein the mounting brings the heat sink into thermal contact with the component.

21. (Original) The method according to claim 20, wherein the mounting brings the heat sink into thermal contact with the component through a thermally conductive material.

22. (Previously presented) The method according to claim 19, wherein the side walls and mounting flanges partially surround the component.

23. (Original) The method according to claim 19, wherein the fastening step includes joining the mounting flanges and the heat sink with at least one member.

24. (Original) The method according to claim 23, wherein the at least one member is one of a screw, a rivet and a bolt.

25. (Original) The method according to claim 19, wherein the fastening includes adhering the

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heat sink to the mounting plate.

26. (Original) The method according to claim 19, further comprising electrically coupling the mounting plate to a potential of the substrate.